

Electronic Patent Application Fee Transmittal

Application Number:	10679787
Filing Date:	06-Oct-2003
Title of Invention:	Connection site coating method and solder joints
First Named Inventor:	Kejun Zeng
Filer:	Yingsheng Tung/Jackie McBride
Attorney Docket Number:	TI-36531

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Filing a brief in support of an appeal	1402	1	500	500
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500